

# NEWS RELEASE



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**AEROFLEX ANNOUNCES  
UT90nHBD 90nm RADIATION-HARDENED-BY-DESIGN LIBRARY  
LICENSE AGREEMENT WITH BOEING SSED**

Colorado Springs, Colorado – Aeroflex Colorado Springs today announced a license agreement and technology development partnership with Boeing Research & Technology’s Solid State Electronics Development (SSED) for 90nm RHBD digital Application Specific Integrated Circuits (ASICs). The two teams are moving to qualify the technology node for aerospace and defense applications while they develop the next generations (45nm SOI and 32nm SOI) of the RHBD library.

“Partnering with Boeing SSED and qualifying the 90nm RHBD library will leverage government investments, Boeing RHBD expertise, and nearly 30 years of Aeroflex Colorado Springs history supplying RadHard integrated circuits to the aerospace and defense communities,” said Roger Van Art, Aeroflex Colorado Springs Vice President of Strategic Business. “Customers will be able to design RadHard ASICs for space applications with this ASIC family to realize significant dynamic power, cell density, and radiation-hardened performance (TID, SEE, Dose Rate) benefits. In addition, Aeroflex Colorado Springs’ CAT1A Trusted accreditation in Design, Test, Assembly, and MPW Aggregation services provides customers with secure and assured access.”

Warren Snapp, Boeing Research & Technology manager of SSED, said that “We are excited to support a leading developer of aerospace electronics to bring this enabling new technology to the market. It will provide aerospace systems developers with access to leading edge integrated circuits to achieve the highest performance and system effectiveness. The program will build on Boeing’s 20 years of experience in developing radiation hardened circuits on leading-edge commercial fabrication processes by use of highly efficient design techniques.

This partnership will leverage the strengths of each company to rapidly transition 90nm design capability to program readiness maturity and support.”

The UT90nHBD offers radiation hardened technology from 100 krad to 1Mrad(Si) total ionizing dose (TID). It's intended to provide single event upset (SEU) at  $<5.0E-9$  errors/bit-day, single event latchup  $>100$  MeV-cm<sup>2</sup>/mg @ 125°C, and dose rate upset at  $>1.0E9$  (Si)/sec. All of Aeroflex's current offerings of Digital RadHard ASICs are QML Q and V qualified.

The Customer Toolkit for the UT90nHBD is available now, optimized for speed, option-based low power operation, and enhanced to meet radiation targets. All QML qualification plans are scheduled to be met by 2013.

Aeroflex Colorado Springs is a supplier of semicustom and standard VLSI circuits and custom circuit card assemblies. Aeroflex has received Qualified Manufacturer List (QML) certification for Class Q, Class T and Class V. Additionally, Aeroflex has received a letter of compliance for ISO 9001 from the Defense Supply Center in Columbus, Ohio.

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For a copy of the UT90nHBD digital ASIC datasheet, call 1-800-645-8862, write Aeroflex, 4350 Centennial Blvd., Colorado Springs, CO 80907, or visit the Aeroflex home page at [www.aeroflex.com/RadHardASIC](http://www.aeroflex.com/RadHardASIC).

### **About Aeroflex Colorado Springs**

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### **About Boeing SSED**

Boeing Solid-State Electronics Development (SSED), part of Boeing Research & Technology, has provided advanced microelectronics designs for The Boeing Company and other companies for 25 years. SSED supports a broad range of integrated circuit applications with special aerospace requirements for RF, analog, mixed-signal, low-power, and extreme environments including radiation hardening.

## **About Aeroflex**

Aeroflex Incorporated is a leading global provider of microelectronic components and test and measurement equipment used by companies in the space, avionics, defense, commercial wireless communications, medical and other markets.

*All statements other than statements of historical fact included in this press release regarding Aeroflex's business strategy and plans and objectives of its management for future operations are forward-looking statements. When used in this press release, words such as "anticipate," "believe," "estimate," "expect," "intend" and similar expressions, as they relate to Aeroflex or its management, identify forward-looking statements. Such forward-looking statements are based on the current beliefs of Aeroflex's management, as well as assumptions made by and information currently available to its management. Actual results could differ materially from those contemplated by the forward-looking statements as a result of certain factors, including but not limited to, adverse developments in the global economy; dependence on growth in customers' businesses; the ability to remain competitive in the markets Aeroflex serves; the inability to continue to develop, manufacture and market innovative, customized products and services that meet customer requirements for performance and reliability; any failure of suppliers to provide raw materials and/or properly functioning component parts; the termination of key contracts, including technology license agreements, or loss of key customers; the inability to protect intellectual property; the failure to comply with regulations such as International Traffic in Arms Regulations and any changes in regulations; the failure to realize anticipated benefits from completed acquisitions, divestitures or restructurings, or the possibility that such acquisitions, divestitures or restructurings could adversely affect Aeroflex; the loss of key employees; exposure to foreign currency exchange rate risks; and terrorist acts or acts of war. Such statements reflect the current views of management with respect to the future and are subject to these and other risks, uncertainties and assumptions. Aeroflex does not undertake any obligation to update such forward-looking statements.*